

RELIABILITY MONITOR REPORT
FOR

CSP Package

Dallas Semiconductor

4401 South Beltwood Parkway
Dallas, TX 75244-3292

This Report was prepared by
Dallas Semiconductor Reliability Engineering

Summary:

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The specific assemblies included in this package monitor are:

ASSY SITE	PINS PACKAGE
Dallas-8"	6 CSP20 RDL

Note: Due to the nature of the construction on this assembly, there is no operating life data collected.

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between and

Assembly Information:

Package Type: CSP RDL (Solder Bump)
Flammability: UL 94-V0
Date Code Range: 0640 to 0642

STORAGE LIFE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
STORAGE LIFE	0642	DS2431	150C	1000 HRS	34	0	
				Total:		0	

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
TEMP CYCLE, SLOW	0642	DS2431	-40C TO +125C	1000 CYS	80	0	
TEMP CYCLE, SLOW	0642	DS2431	-40C TO +125C	1000 CYS	80	0	
				Total:		0	

TEMPERATURE HUMIDITY BIAS

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
BIASED MOISTURE	0642	DS2431	85/85, 5.5 VOLTS	1000 HRS	80	0	
BIASED MOISTURE	0642	DS2431	85/85, 5.5 VOLTS	1000 HRS	80	0	
				Total:		0	

UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
AUTOCLAVE	0640	DS2431	121C, 2 ATM STEAM, UNBIASED	168 HRS	231	0	
				Total:		0	